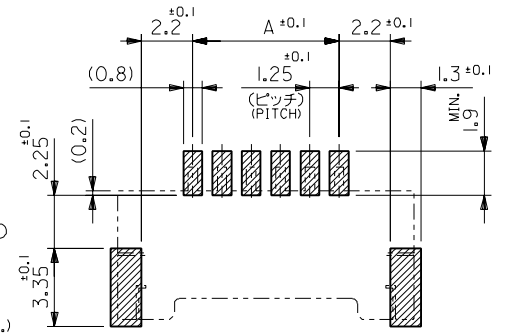
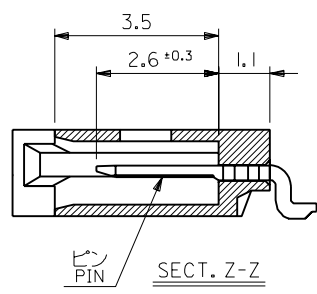
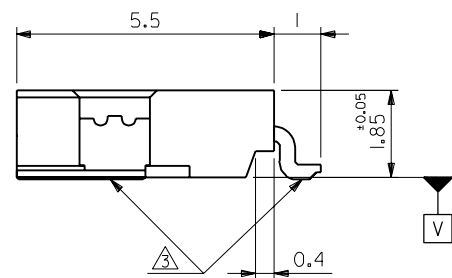
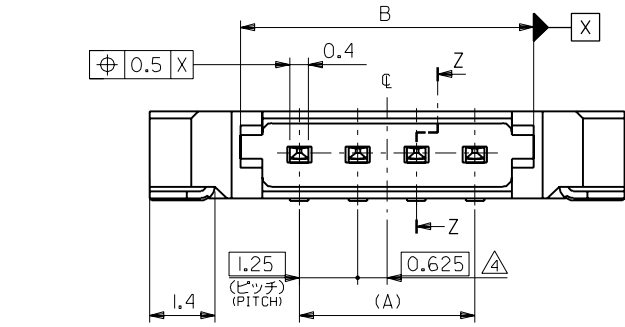


注記 NOTES

1. 嵌合相手: 51146 シリーズ
MATES WITH : 51146 SERIES
2. ロック窓は2、3極品は1箇所、4極品以上は2箇所とする。
LOCKING WINDOW : ONE PLACE FOR 2 AND 3 CIRCUIT PRODUCTS AND TWO PLACES FOR MORE THAN 3 CIRCUIT PRODUCTS.
3. 基準面 [V] からのソルダーテールと金具の半田付け面のズレ量は、上方向に 0.05MAX. 下方向 0.15MAX. とし、20 極以下の相互のバラツキ量は 0.IMAX. とする。
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM [V] : UPPER DIRECTION 0.05MAX. : LOWER DIRECTION 0.15MAX. : OFFSET BETWEEN UPPER AND LOWER 0.IMAX. (UNDER 20 CKTS.)
4. 偶数極の製品に適用。
APPLY EVEN CIRCUIT PRODUCTS.
5. 材質 MATERIAL
ウエハー WAFER : PPHS , UL94V-0
ピン: リン青銅 (コンタクト部: 金メッキ、テール部: 半田メッキ)
PIN : PHOS-BRO (CONTACT : Au PLATING, TAIL : Sn-Pb PLATING)
金具: リン青銅 (半田メッキ)
FITTING NAIL : PHOS-BRO (Sn-Pb PLATING)



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM. (REF.)



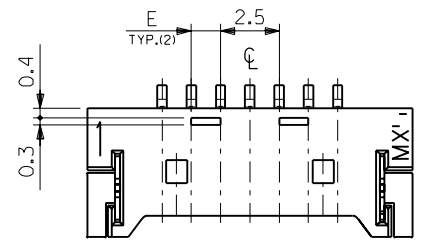
8.75	22.5	30.15	26.27	23.75	53780-2010	20
7.5	20	27.65	23.77	21.25	-1810	18
6.25	17.5	25.15	21.27	18.75	-1610	16
6.25	16.25	23.9	20.02	17.5	-1510	15
5	15	22.65	18.77	16.25	-1410	14
3.75	12.5	20.15	16.27	13.75	-1210	12
2.5	10	17.65	13.77	11.25	-1010	10
2.5	8.75	16.4	12.52	10	-0910	9
1.25	7.5	15.15	11.27	8.75	-0810	8
1.25	6.25	13.9	10.02	7.5	-0710	7
--	5	12.65	8.77	6.25	-0610	6
--	3.75	11.4	7.52	5	-0510	5
--	2.5	10.15	6.27	3.75	-0410	4
--	--	8.9	5.02	2.5	-0310	3
--	--	7.65	3.77	1.25	53780-0210	2
E	D	C	B	A	ENG. NO.	CKT. 極数

G	変更 REVISED	(JC2000-0862)	S.M. T.Y	'00/6/21
F	変更 REVISED	(JC80823)	S.M. S.K	'98/4/22
E	変更 REVISED	(JC70644)	S.M. Y.M	'91/1/27
D	変更 REVISED	(JC70592)	S.M. Y.M	'91/1/13
C	変更 REVISED	(JC70159)	S.M. Y.M	'96/8/9
B	変更 REVISED	(JC60804)	S.M. M.F	'96/5/1
A	変更 REVISED	(JC60541)	S.M. H.H	'96/2/6
O	新規作成 PROPOSED	(JC60428)	Y.M. H.H	'95/12/25
角 度 ANGLE		±3°		
30 以上 OVER		+0.3		
10 以上 30 未満 UNDER		+0.25		
10 未満 UNDER		+0.2		
一 般 公 差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. 日付 DATE

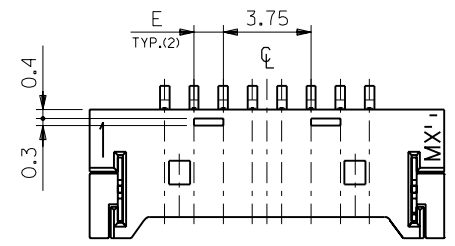
材料 MATERIAL	注記参照 SEE NOTES
仕上げ FINISH	--/--
適用電線範囲 WIRE RANGE	--/--
被覆外径 INS. RANGE	--/--
DRAWN BY '95/12/25 Y.MIZUNO	
CHK'D BY '00/6/21 T.YAMAGUCHI	
APP'D BY '00/6/21 M.FUKUSHIMA	
尺 度 SCALE	--/--

molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
REVISE ONLY ON CAD SYSTEM	
TITLE 名称	
1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR S.M.T.	
DWG. NO. (SHEET 1 OF 2) REV	
SD-53780-***10 G	

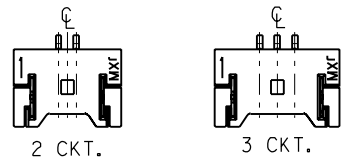
DWG. NO. SD-53780-***10



7~19極の奇数極に適用
APPLY FOR ODD CIRCUITS OF 7~19



8~20極の偶数極に適用
APPLY FOR EVEN CIRCUITS OF 8~20



ロック形状図
LOCK CONFIGURATION

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

角度 ANGLE	+3°
30 以上 OVER	+0.3
10 以上 30 未満 UNDER	+0.25
10 未満 UNDER	+0.2
一般公差 GENERAL TOLERANCES	

G 変更 REVISD (JC2000-0862)	S.M. T.Y	'00/6/21
F 変更 REVISD (JC800823)	S.M. S.K	'98/4/22
E 変更 REVISD (JC70644)	S.M. Y.M	'97/1/27
D 変更 REVISD (JC70592)	S.M. Y.M	'97/1/13
C 変更 REVISD (JC70159)	S.M. Y.M	'96/8/9
B 変更 REVISD (JC60804)	S.M. M.F	'96/5/11
A 変更 REVISD (JC60541)	S.M. H.H	'96/2/16
O 新規作成 PROPOSED (JC60420)	Y.M. H.H	'95/12/25
記号 LTR	変更内容 REVISION RECORD	DR. CHR. 日付 DATE

材料 MATERIAL	注記参照 SEE NOTES	モレックス株式会社 MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
仕上げ FINISH	— # —	REVISION ONLY ON CAD SYSTEM
適用電線範囲 WIRE RANGE	— # —	TITLE 名称
被覆外径 INS. RANGE	— # —	I.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR S.M.T.
DRAWN BY '95/12/25 Y.MIZUNO	CHK'D BY '00/6/21 T.YAMAGUCHI	DWG. NO. (SHEET 2 OF 2) REV
APP'D BY '00/6/21 M.FUKUSHIMA	尺度 SCALE	SD-53780-***10 G

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX(JAPAN) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
本図面は日本モレックス(株)の所有する情報を含むもので 当社の許可なく複製を禁止する。
EN-01C(032)MXJ-32

DWG. NO. SD-53780-***90

E

D

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

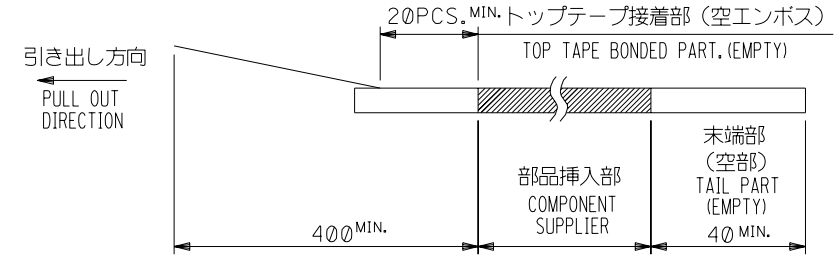
B

A

8 7 6 5 4 3 2 1

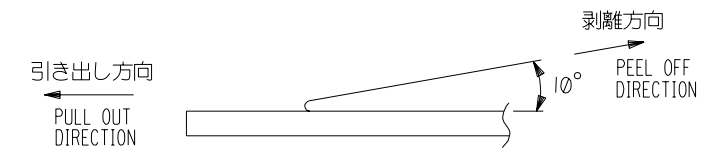
NOTES

1. 梱包数量：1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH
20PCS. MIN. トップテープ接着部 (空エンボス)
TOP TAPE BONDED PART. (EMPTY)



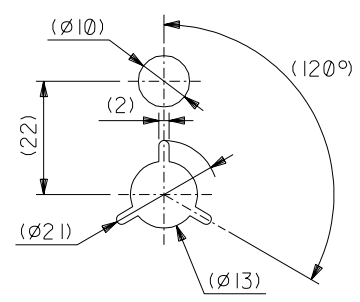
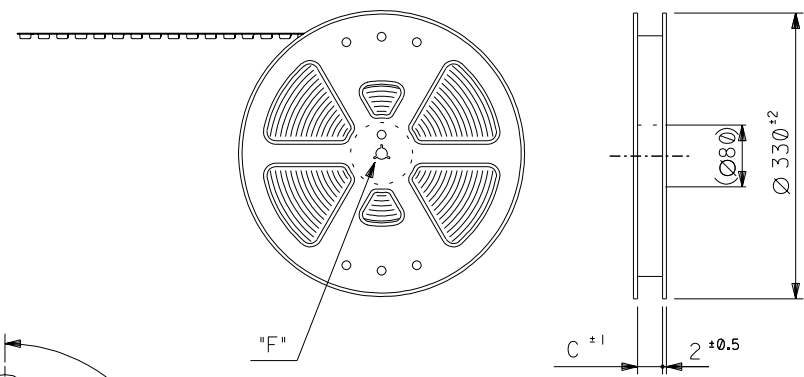
3. トップテープの剥離強度：0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(剥離方向は下図参照)

尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



4. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)
トップテープ(TOPTAPE)：PET, PE, PEF
リール(REEL)：ポリスチレン(P.S) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>

引き出し方向
PULL OUT
DIRECTION



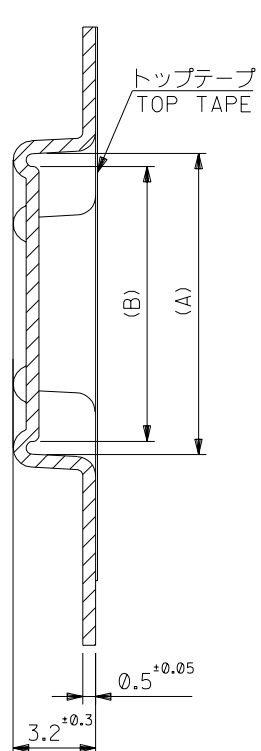
DETAIL "F"

				材料 MATERIAL		注記参照 SEE NOTE		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
		N 変更 REVISIED (J2002-2940)		N.I K.A '02/05/27				REVISE ONLY ON CAD SYSTEM	
		M 変更 REVISIED (JC2001-0424)		K.K.T.V '00/12/16		仕上げ FINISH		TITLE 名称	
角度 ANGLE		±3°		L 変更 REVISIED (JC2001-0318)		S.M.T.V '00/10/27		適用電線範囲 WIRE RANGE	
30 以上 OVER		+0.3		K 変更 REVISIED (JC90327)		S.M.S.K '98/12/1		被覆外径 INS. RANGE	
10 以上 OVER 30 未満 UNDER		+0.25		J 変更 REVISIED (JC80706)		T.A.S.K '98/3/11		DRAWN BY '95/12/27	
10 未満 UNDER		+0.2		H 再作図と変更 REDRAWN & REVISIED (JC80662)		T.N.S.K '98/2/20		CHK'D BY '02/05/27	
一般公差 GENERAL TOLERANCES		記号 LTR		変更内容 REVISION RECORD		DR. CHK. DATE		APP'D BY '02/05/27	
						T.YAMAGUCHI		尺度 SCALE	
								DWG. NO. (SHEET 1 OF 3)	
								SD-53780-***90	
								REV N	

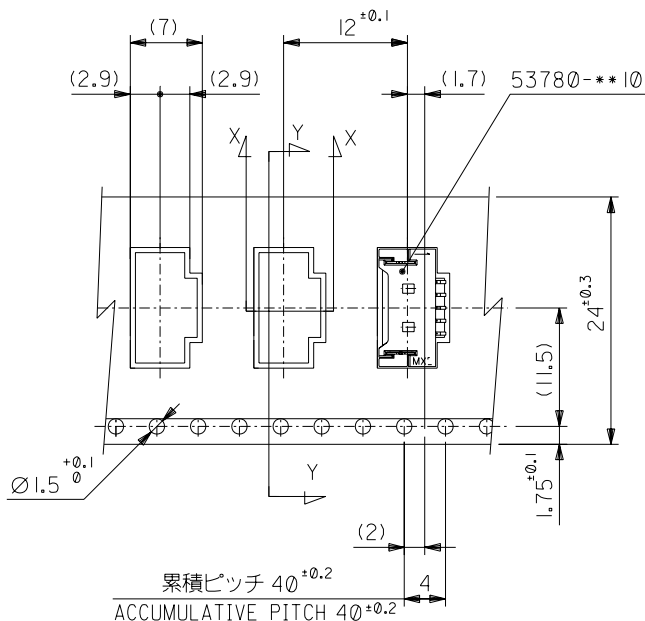
8 7 6 5 4 3 2 1

5378090.S0

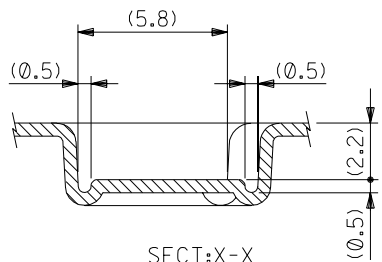
DWG. NO. SD-53780-**-90



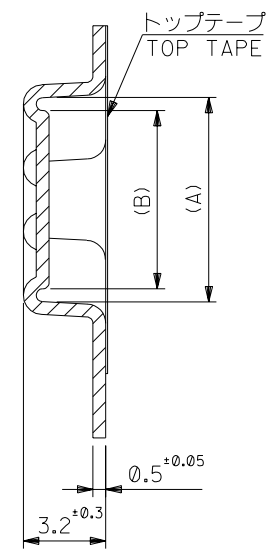
SECT:Y-Y
(SCALE 5:1)



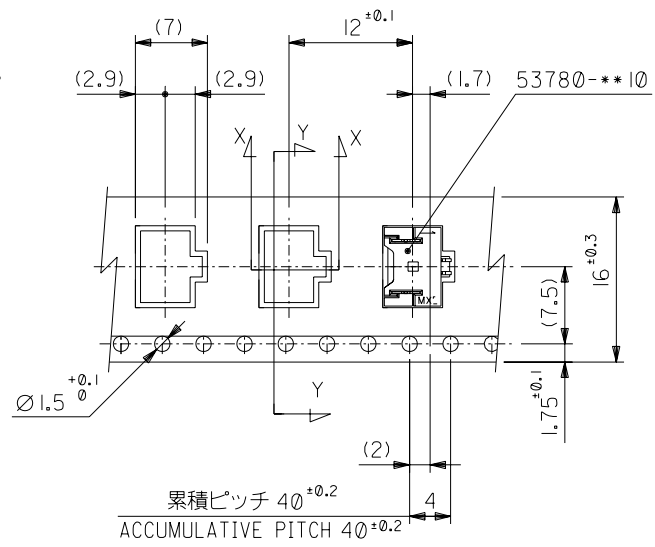
引き出し方向
PULL OUT DIRECTION



SECT:X-X
(SCALE 5:1)



SECT:Y-Y
(SCALE 5:1)



引き出し方向
PULL OUT DIRECTION

キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	ENG. NO.	種数 CKT.
24	25.5	11.75	16.7	53780-0990	9
		10.5	15.45	53780-0890	8
		9.25	14.2	53780-0790	7
		8	12.95	53780-0690	6
		6.75	11.7	53780-0590	5
16	17.5	5.5	10.45	53780-0490	4
		4.25	9.2	53780-0390	3
		3	7.95	53780-0290	2

記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE	材料 MATERIAL	材料 SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3
N	変更 (J2002-2940) REVISED	N.I.	'02/05/27	仕上げ FINISH	—
M	変更 (JC2001-0424) REVISED	K.K.	'00/12/16		
L	変更 (JC2001-0318) REVISED	S.M.	'00/10/27	適用電線範囲 WIRE RANGE	—
K	変更 (JC90327) REVISED	S.M.	'98/12/1	被覆外径 INS. RANGE	—
J	変更 (JC80706) REVISED	T.A.	'98/3/11	DRAWN BY '95/12/27 S.MATSUZAKI	CHK'D BY '02/05/27 K.ASAKAWA
H	再作図と変更 REDRAWN & REVISED (JC80662)	T.N.	'98/2/20	APP'D BY '02/05/27 T.YAMAGUCHI	尺 度 SCALE

MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
1.25 W/B WAFER ASS'Y
EMBOSSD TAPE PACKAGE

DWG. NO. (SHEET 2 OF 3) REV
SD-53780-**-90 N

角度 ANGLE	公差
30° 以上 OVER	+0.3
10° 以上 30° 未満 OVER	+0.25
未満 10° UNDER	+0.2
一般公差 GENERAL TOLERANCES	

DWG. NO. SD-53780-***90

F

D

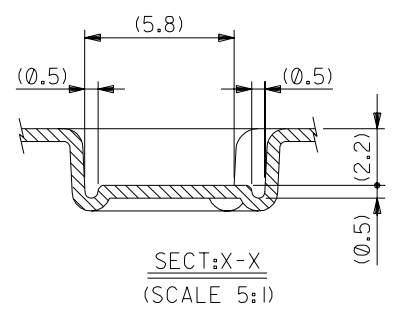
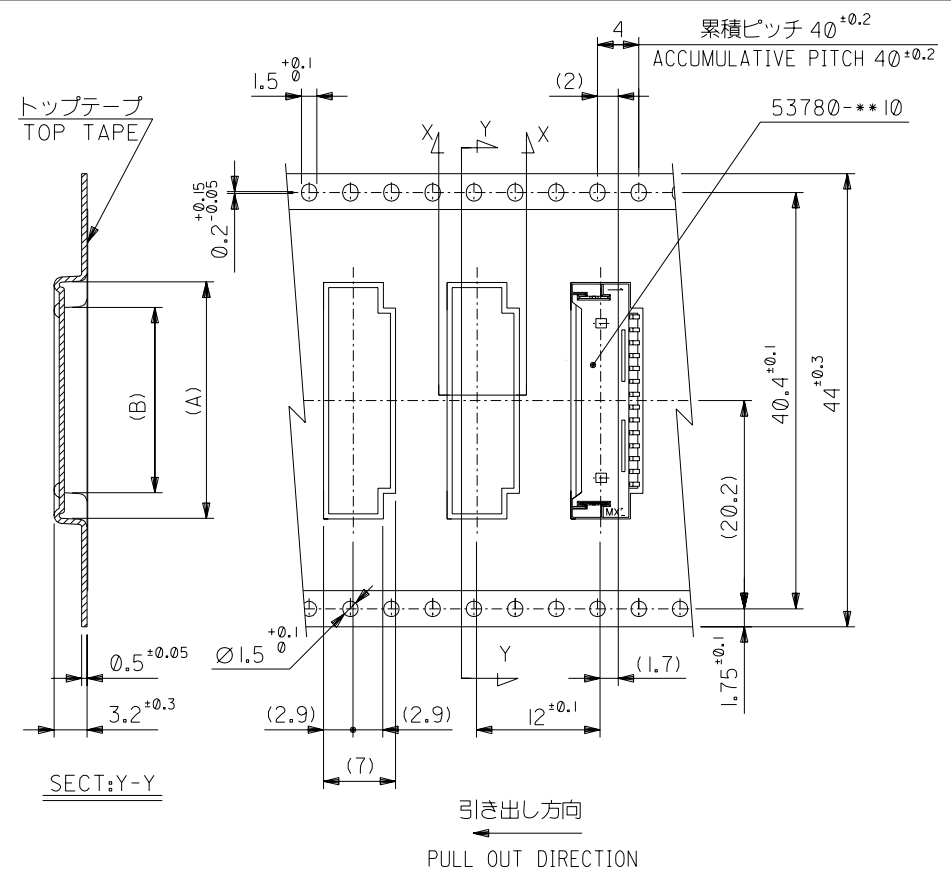
C

B

A

1:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1



44	45.5	28	32.95	53780-2290	22	
		25.5	30.45	53780-2090	20	
		25.5	27.95	53780-1890	18	
		19.25	24.2	53780-1590	15	
		18	22.95	53780-1490	14	
		15.5	20.45	53780-1290	12	
キャリアテープ幅 CARRIER TAPE WIDTH		C	(B)	(A)	ENG. NO.	種数 CKT.

材料 MATERIAL SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3				molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
N	変更 REVISED (J2002-2940)	N.I	'02/05/27	REVISE ONLY ON CAD SYSTEM	
M	変更 REVISED (JC2001-0424)	K.K	'00/12/16	TITLE 名称 1.25 W/B WAFER ASS'Y EMBOSSD TAPE PACKAGE	
L	変更 REVISED (JC2001-0318)	S.M	'00/10/27	適用電線範囲 WIRE RANGE	---
K	変更 REVISED (JC90327)	S.M	'98/12/1	被覆外径 INS. RANGE	---
J	変更 REVISED (JC80706)	T.A	'98/3/11	DRAWN BY '95/12/27 S.MATSUZAKI	
H	再作図と変更 REDRAWN & REVISED (JC80662)	T.N	'98/2/20	CHK'D BY '02/05/27 K.ASAKAWA	
一般公差 GENERAL TOLERANCES		DR.	日付 DATE	尺度 SCALE	---
記号 LTR	変更内容 REVISION RECORD	DR.	日付 DATE	尺度 SCALE	---

DWG. NO. (SHEET 3 OF 3) REV N
SD-53780-***90

8 7 6 5 4 3 2 1

DWG. NO. SD-53780-003

F

E

D

D

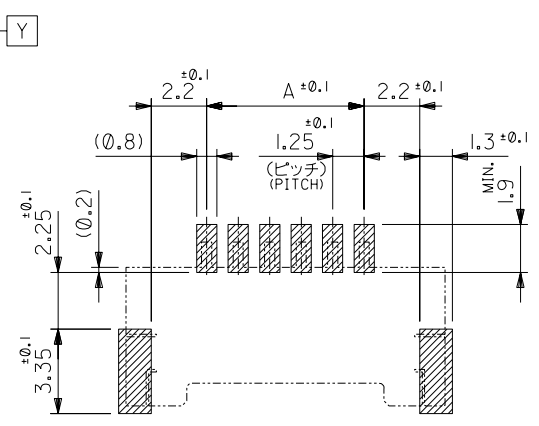
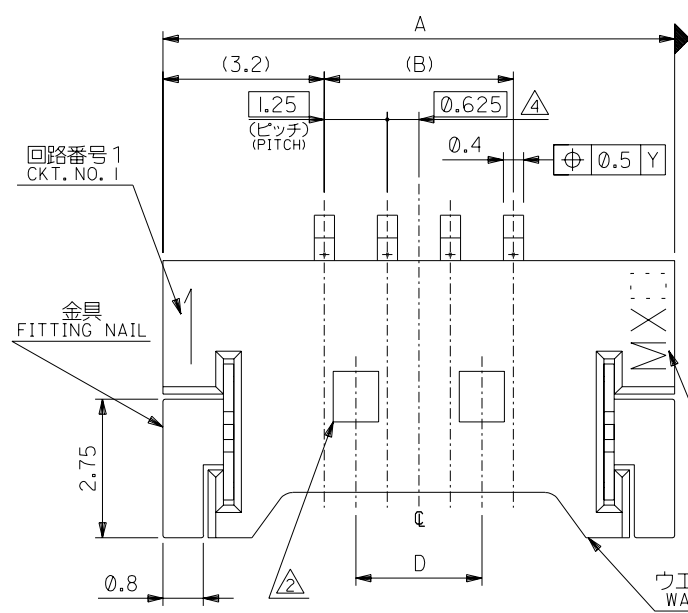
V

C

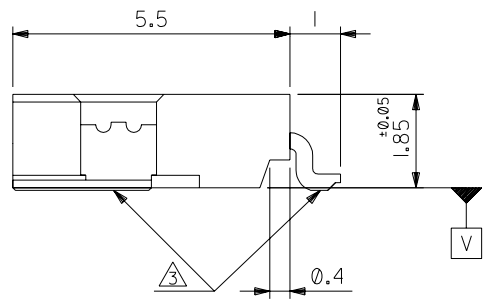
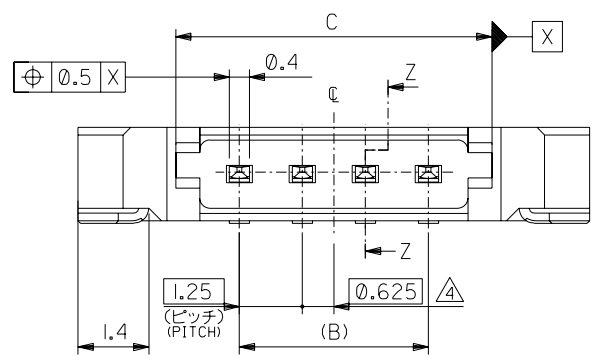
B

DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM. (REF.)



注記 NOTES

1. 嵌合相手: 51146 シリーズ
MATES WITH: 51146 SERIES
2. ロック窓は2、3極品は1箇所、4極品以上は2箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CIRCUIT PRODUCTS AND TWO PLACES FOR MORE THAN 3 CIRCUIT PRODUCTS.
3. 基準面[V]からのソルダテールと金具の半田付け面のズレ量は、上方向に0.05MAX. 下方向0.15MAX. とし、20極以下の相互のパラツキ量は0.1MAX. とする。
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM [V]: UPPER DIRECTION 0.05MAX. LOWER DIRECTION 0.15MAX. OFFSET BETWEEN UPPER AND LOWER 0.1MAX. (UNDER 20 CKTS.)
4. 偶数極の製品に適用。
APPLY EVEN CIRCUIT PRODUCTS.
5. 材質 MATERIAL
ウエハー WAFER: PPHS, UL94V-0
ピン: リン青銅(下地: ニッケル, コンタクト部: 金メッキ, テール部: 錫メッキ)
PIN: PHOS-BRO (UNDER: NICKEL PLATING, CONTACT: GOLD PLATING, TAIL: TIN PLATING)
金具: リン青銅(下地: ニッケル, 錫メッキ)
FITTING NAIL: PHOS-BRO (TIN OVER NICKEL PLATING)
6. 本製品は 53780-**10/-**18 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53780-**10/-**18.

8.75	22.5	26.27	23.75	30.15	53780-2019	20
7.5	20	23.77	21.25	27.65	-1819	18
6.25	16.25	20.02	17.5	23.9	-1519	15
5	15	18.77	16.25	22.65	-1419	14
3.75	12.5	16.27	13.75	20.15	-1219	12
2.5	8.75	12.52	10	16.4	-0919	9
1.25	7.5	11.27	8.75	15.15	-0819	8
1.25	6.25	10.02	7.5	13.9	-0719	7
--	5	8.77	6.25	12.65	-0619	6
--	3.75	7.52	5	11.4	-0519	5
--	2.5	6.27	3.75	10.15	-0419	4
--	--	5.02	2.5	8.9	-0319	3
--	--	3.77	1.25	7.65	53780-0219	2
E	D	C	B	A	MATERIAL NO.	CKT. 極数

MODEL NO.	53780-**19	DIMENSIONS:	SHT	REV
		<input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY		
		<input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY		

64NO. DRWN: CH'K: APPR: 63NO. DRWN: CH'K: APPR: 62NO. DRWN: CH'K: APPR: 61NO. DRWN: CH'K: APPR: 60NO. DRWN: CH'K: APPR: 59NO. DRWN: CH'K: APPR: 58NO. DRWN: CH'K: APPR: 57NO. DRWN: CH'K: APPR: 56NO. DRWN: CH'K: APPR: 55NO. DRWN: CH'K: APPR: 54NO. DRWN: CH'K: APPR: 53NO. DRWN: CH'K: APPR: 52NO. DRWN: CH'K: APPR: 51NO. DRWN: CH'K: APPR: 50NO. DRWN: CH'K: APPR: 49NO. DRWN: CH'K: APPR: 48NO. DRWN: CH'K: APPR: 47NO. DRWN: CH'K: APPR: 46NO. DRWN: CH'K: APPR: 45NO. DRWN: CH'K: APPR: 44NO. DRWN: CH'K: APPR: 43NO. DRWN: CH'K: APPR: 42NO. DRWN: CH'K: APPR: 41NO. DRWN: CH'K: APPR: 40NO. DRWN: CH'K: APPR: 39NO. DRWN: CH'K: APPR: 38NO. DRWN: CH'K: APPR: 37NO. DRWN: CH'K: APPR: 36NO. DRWN: CH'K: APPR: 35NO. DRWN: CH'K: APPR: 34NO. DRWN: CH'K: APPR: 33NO. DRWN: CH'K: APPR: 32NO. DRWN: CH'K: APPR: 31NO. DRWN: CH'K: APPR: 30NO. DRWN: CH'K: APPR: 29NO. DRWN: CH'K: APPR: 28NO. DRWN: CH'K: APPR: 27NO. DRWN: CH'K: APPR: 26NO. DRWN: CH'K: APPR: 25NO. DRWN: CH'K: APPR: 24NO. DRWN: CH'K: APPR: 23NO. DRWN: CH'K: APPR: 22NO. DRWN: CH'K: APPR: 21NO. DRWN: CH'K: APPR: 20NO. DRWN: CH'K: APPR: 19NO. DRWN: CH'K: APPR: 18NO. DRWN: CH'K: APPR: 17NO. DRWN: CH'K: APPR: 16NO. DRWN: CH'K: APPR: 15NO. DRWN: CH'K: APPR: 14NO. DRWN: CH'K: APPR: 13NO. DRWN: CH'K: APPR: 12NO. DRWN: CH'K: APPR: 11NO. DRWN: CH'K: APPR: 10NO. DRWN: CH'K: APPR: 9NO. DRWN: CH'K: APPR: 8NO. DRWN: CH'K: APPR: 7NO. DRWN: CH'K: APPR: 6NO. DRWN: CH'K: APPR: 5NO. DRWN: CH'K: APPR: 4NO. DRWN: CH'K: APPR: 3NO. DRWN: CH'K: APPR: 2NO. DRWN: CH'K: APPR: 1NO. DRWN: CH'K: APPR:	04/04/15 02004-3817 T.UENO M.SASAO M.SASAO	MATERIAL 材料 注記参照 SEE NOTES FINISH 仕上げ 注記参照 SEE NOTES WIRE RANGE 適用電線範囲 INS. RANGE 被覆外径	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未満 ±0.2 10 OVER 以上 30 UNDER 未満 ±0.25 30 OVER 以上 ±0.3 ANGLE 角度 ±3°	SCALE 10:1 DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH DRAWN BY & DATE T.UENO 04/04/15 CHECKED BY & DATE M.SASAO 04/04/15 APPROVED BY & DATE M.SASAO 04/04/15 CAD FILENAME SD-53780-003.S01	TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR S.M.T. -LEAD FREE- MOLEX INCORPORATED MATERIAL NO. SEE CHART DRAWING NO. SD-53780-003 SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION. SIZE B
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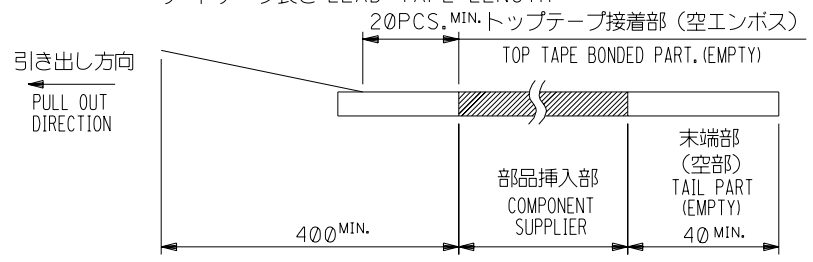
8 7 6 5 4 3 2 1 EN-02J(097) MXJ-54

DWG. NO. SD-53780-004

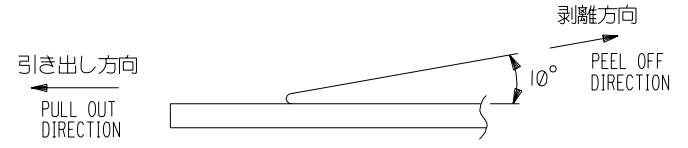
8 7 6 5 4 3 2 1

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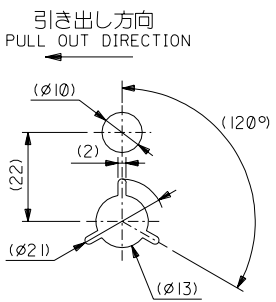
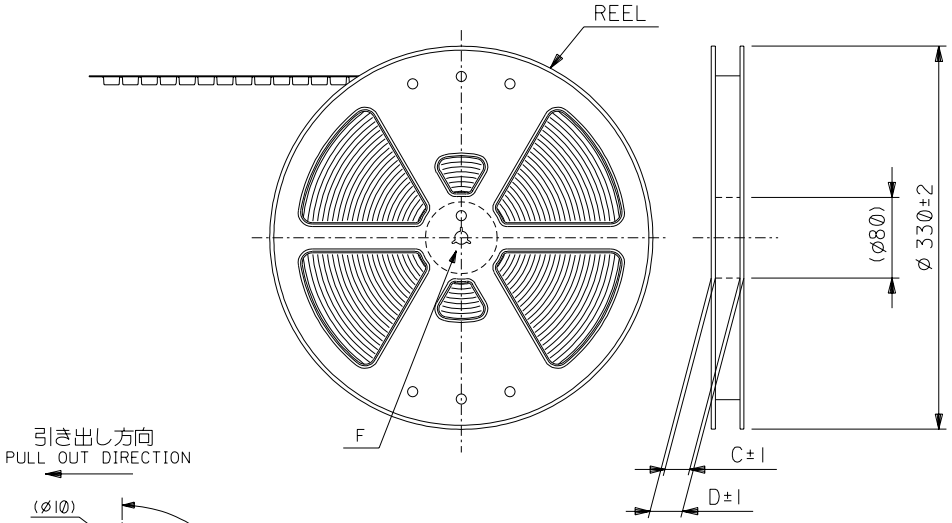
- 梱包数量：1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：0.1N ~ 1.3N(10gf ~ 130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 1.3N(10gf ~ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)
トップテープ (TOPTAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は 53780-**-90/-**-80 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53780-**-90/-**-80.



DETAIL F

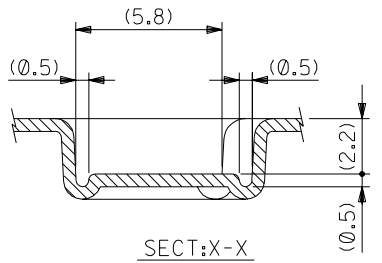
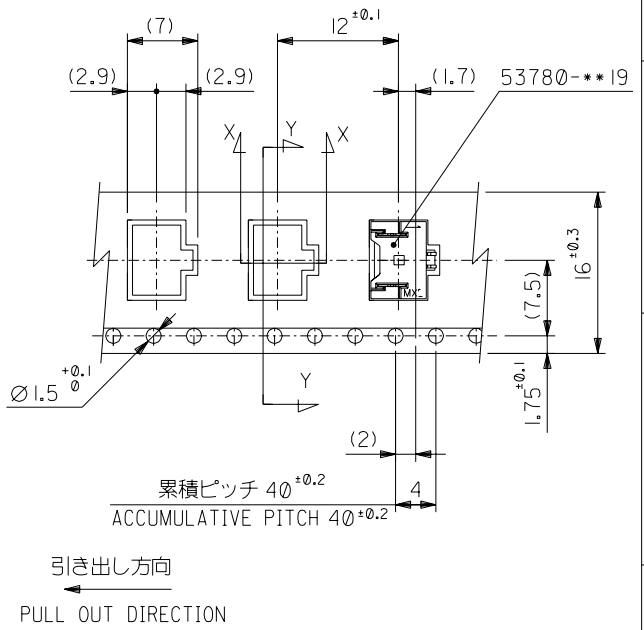
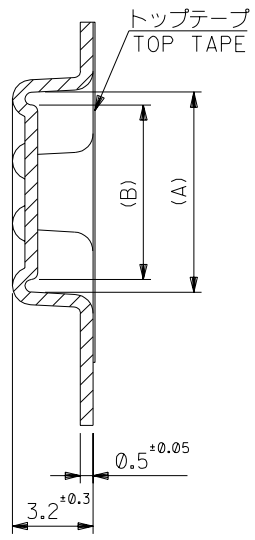
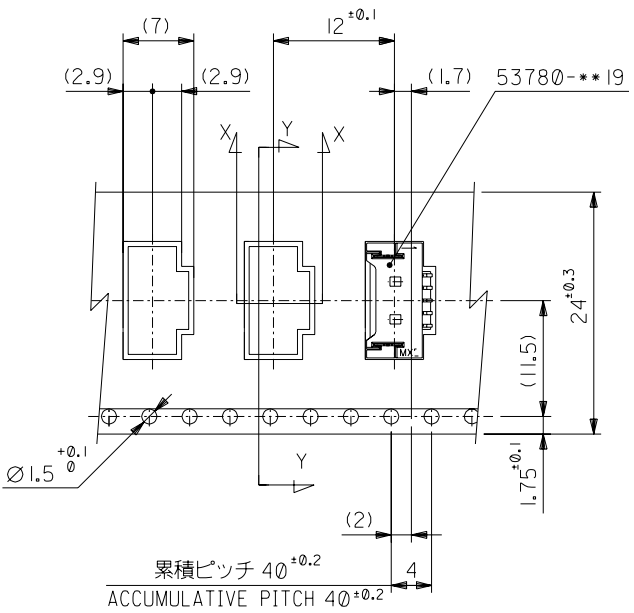
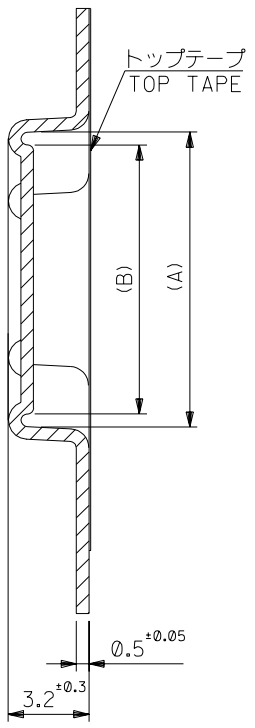
DO NOT SCALE DRAWING

64 NO. DRWN: CH'K: APPR: 63 NO. DRWN: CH'K: APPR: 62 NO. DRWN: CH'K: APPR: 61 NO. DRWN: CH'K: APPR:		RELEASED '04/04/15 60 NO. J2004-3817 DRWN: T.UENO CH'K: M.SASAO APPR: M.SASAO	MATERIAL 材料 //	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未満 ±0.2 10 OVER 以上 30 UNDER 未満 ±0.25 30 OVER 以上 ±0.3	SCALE 1:1 DESIGN UNITS ① mm ② INCH DRAWN BY & DATE T.UENO '04/04/15 CHECKED BY & DATE M.SASAO '04/04/15 APPROVED BY & DATE M.SASAO '04/04/15	MODEL NO. 53780-**-70 DIMENSIONS: ① mm ② INCH ③ mm ONLY SHT 1/3 REV B TITLE: 1.25 W/B WAFER ASS'Y EMBOSSED TAPE PACKAGE -LEAD FREE-
WIRE RANGE 適用電線範囲 // ANGLE 角度 ±3°			MOLEX INCORPORATED		CAD FILENAME SD-53780-004.S01 MATERIAL NO. SEE CHART DRAWING NO. SD-53780-004 SHEET NO. 1/3	
INS. RANGE 被覆外径 //			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B	

8 7 6 5 4 3 2 1 EN-02J(097) MXJ-54

DWG. NO. SD-53780-004

8 7 6 5 4 3 2 1



24	29.4	25.4	11.75	16.7	53780-0970	9			
			10.5	15.45	53780-0870	8			
			9.25	14.2	53780-0770	7			
			8	12.95	53780-0670	6			
			6.75	11.7	53780-0570	5			
			5.5	10.45	53780-0470	4			
16	21.4	17.4	4.25	9.2	53780-0370	3			
			3	7.95	53780-0270	2			
			キャリアテープ幅 CARRIER TAPE WIDTH				D	C	(B)

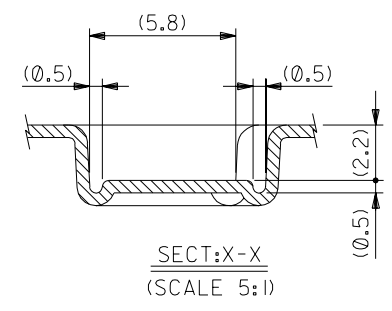
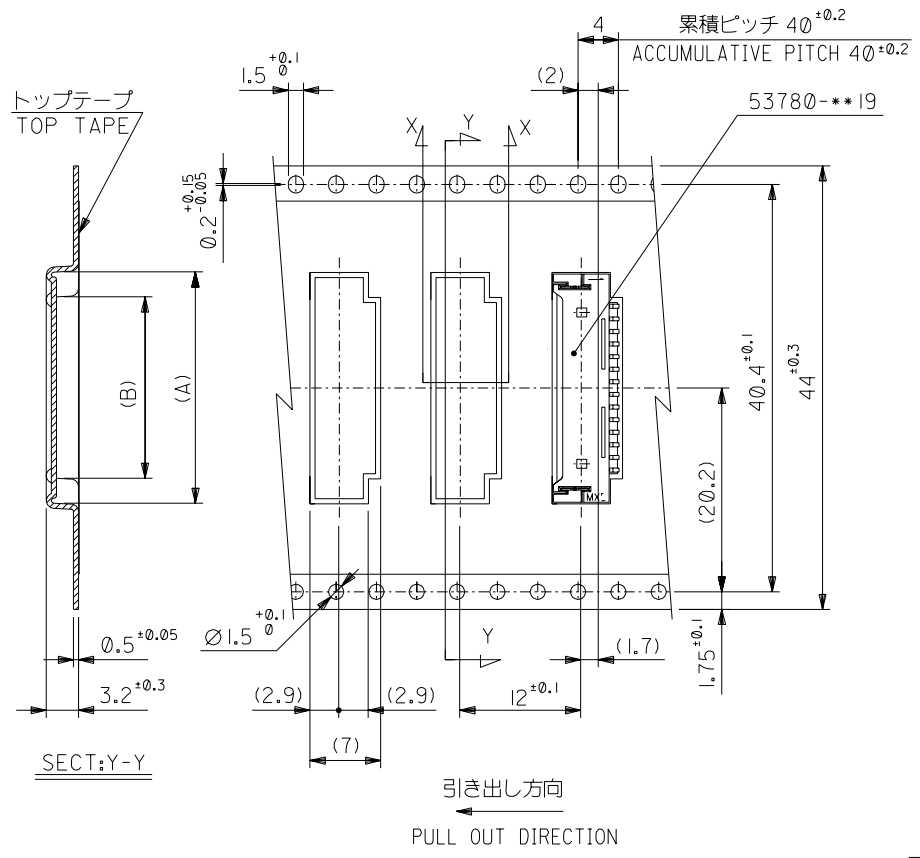
DO NOT SCALE DRAWING

64NO. DRWN: CHK: APPR:	63NO. DRWN: CHK: APPR:	62NO. DRWN: CHK: APPR:	61NO. DRWN: CHK: APPR:	RELEASED '04/04/15 880NO.J2004-3817 DRWN: T.UENO CHK: M.SASAO APPR: M.SASAO	MATERIAL 材料 //
FINISH 仕上げ //					
WIRE RANGE 適用層線範囲 //					
INS. RANGE 被覆外径 //					

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE 2 : 1	DESIGN UNITS mm INCH	MODEL NO. 53780-***70	DIMENSIONS: mm INCH mm ONLY	SHT REV OTHERWISE ON CAD ONLY
10 UNDER 未満 ±0.2 10 OVER 以上 30 UNDER 未満 ±0.25 30 OVER 以上 ±0.3	DRAWN BY & DATE T.UENO '04/04/15	TITLE: 1.25 W/B WAFER ASS'Y EMBOSSED TAPE PACKAGE -LEAD FREE-			
ANGLE 角度 ±3°	CHECKED BY & DATE M.SASAO '04/04/15	MOLEX INCORPORATED			
CAD FILENAME SD-53780-004.S02		MATERIAL NO. SEE CHART	DRAWING NO. SD-53780-004	SHEET NO. 2/3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					

8 7 6 5 4 3 2 1 EN-02J(097) MXJ-54

DWG. NO. SD-53780-004



44	49.4	45.4	(B)	(A)	MATERIAL NO.	極数	
			25.5	30.45	53780-2070	20	
			25.5	27.95	53780-1870	18	
			19.25	24.2	53780-1570	15	
			18	22.95	53780-1470	14	
			15.5	20.45	53780-1270	12	
キャリアテープ幅 CARRIER TAPE WIDTH		D	C	(B)	(A)	MATERIAL NO.	極数 CKT.

DO NOT SCALE DRAWING

64 NO. DRWN: CH'K: APPR:	63 NO. DRWN: CH'K: APPR:	62 NO. DRWN: CH'K: APPR:	61 NO. DRWN: CH'K: APPR:	RELEASED '04/04/15 60 NO. J2004-3817 DRWN: T.UENO CH'K: M.SASAO APPR: M.SASAO	MATERIAL 材料 //	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE //	MODEL NO. DESIGN UNITS 53780-**70 <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT REV
					FINISH 仕上げ //	10 UNDER 未満 ±0.2	DRAWN BY & DATE T.UENO '04/04/15	TITLE: 1.25 W/B WAFER ASS'Y EMBOSSED TAPE PACKAGE -LEAD FREE- MOLEX INCORPORATED		
					WIRE RANGE 適用電線範囲 //	10 OVER 30 UNDER 以上 未満 ±0.25	CHECKED BY & DATE M.SASAO '04/04/15			
					INS. RANGE 被覆外径 //	30 OVER 以上 ±0.3	APPROVED BY & DATE M.SASAO '04/04/15			
						ANGLE 角度 ±3°	CAD FILENAME SD-53780-004.S03	MATERIAL NO. SEE CHART	DRAWING NO. SD-53780-004	SHEET NO. 3/3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B
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